Hybrid 3z100 Traveler

February 17, 2000

1 Connectivity

Repairs on shorts:

Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 3Z100 has die: 061-039 061-040 061-041

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 3z100 classification info. Created 15:16:16 01/14/00

Hybrid 3z100 quality: fair
Chip classification: fair good good
Bad channels: none
Bad cells: none
Random bad capacitors (chip-cell-channel): 0-11-113 0-12-113 0-14-112
   0-14-113 0-16-112 0-16-113 0-18-112 0-18-113 0-27-112 0-27-113 0-28-113
   0-29-113 0-40-113 0-8-112 0-8-113 0-9-113
Channels at pedestal needed for DCMS: 34.7 35.6 33.6
```

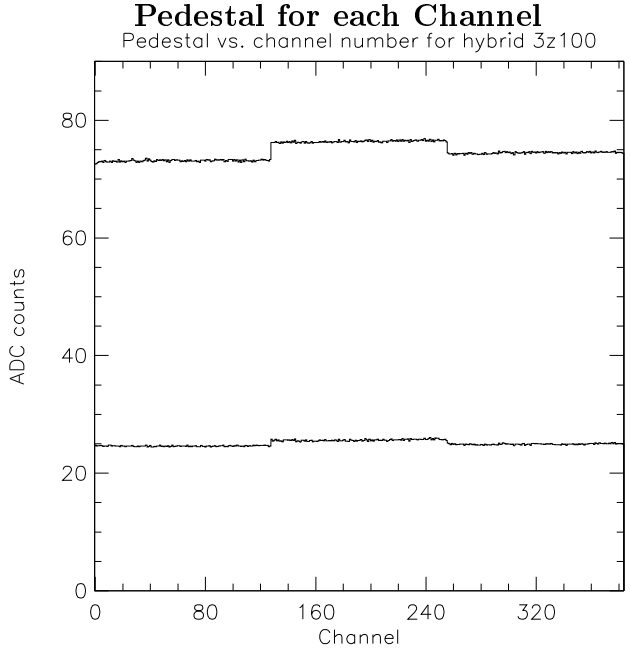
4 Comments

Noisy chanel 113. Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

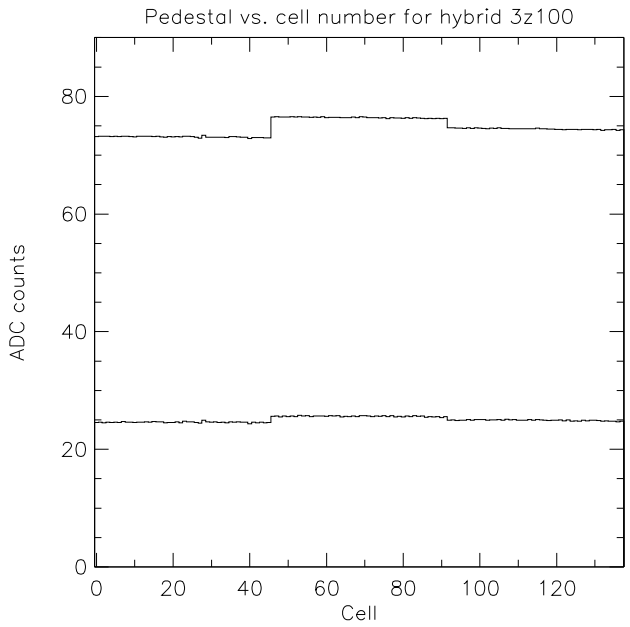
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

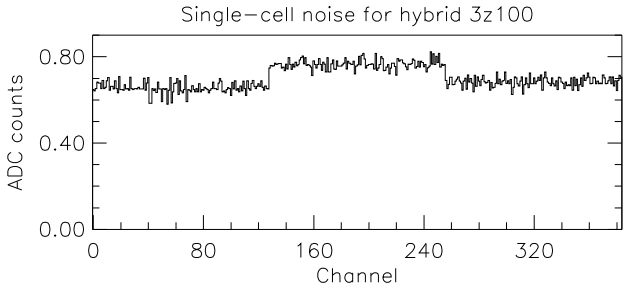
Pedestal vs. Pipeline Cell ID

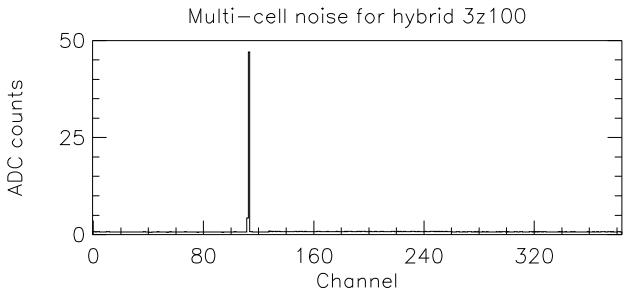


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

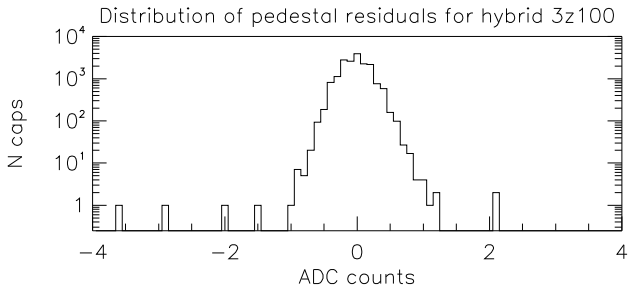
RMS Noise

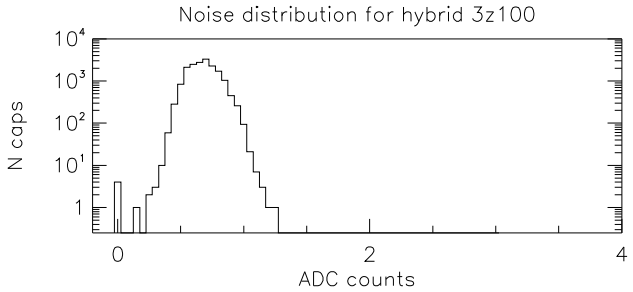




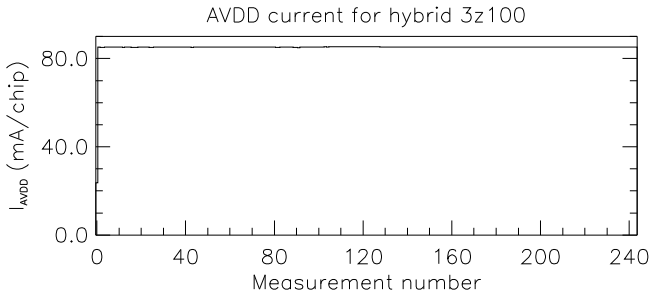
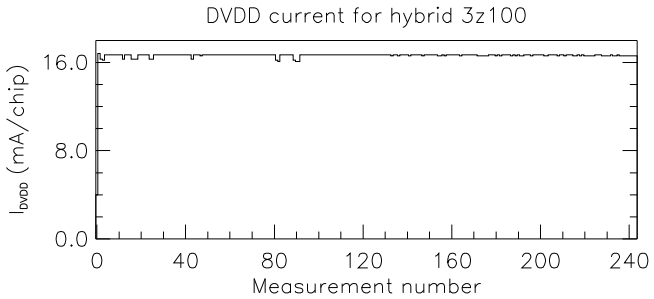
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in